#### **Description**

The FQD20N06 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

Battery protection of in other Switching application



TO-252-2L

#### **General Features**

 $V_{DS} = 60V I_{D} = 20 A$ 

 $R_{DS(ON)} < 32m\Omega$  @  $V_{GS}=10V$ 

### **Application**

Battery protection

Load switch

Uninterruptible power supply

# PIN1 G PIN3 S

N-Channel MOSFET

## **Package Marking and Ordering Information**

Product ID	Pack	Brand	Qty(PCS)
FQD20N06	TO-252-2L	HXY MOSFET	2500

## Absolute Maximum Ratings (T<sub>C</sub>=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	Drain-Source Voltage 60	
Vgs	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	20	А
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	10	А
МП	Pulsed Drain Current <sup>2</sup>	80	А
EAS	Single Pulse Avalanche Energy <sup>3</sup>	38	mJ
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	34.7	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C



### Electrical Characteristics (T<sub>J</sub> = 25°C, unless otherwise noted)

Parameter		Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static Characteristics				•				
Drain-Source Breakdown Vo	oltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	60	-	-	V	
Gate-Body Leakage Current		lgss	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA	
Zero Gate Voltage Drain Current	TJ=25°C		V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V	-	-	1	μA	
	TJ=100℃	IDSS		-	-	100		
Gate-Threshold Voltage		V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1.2	1.7	2.5	V	
		_	V <sub>GS</sub> = 10V, I <sub>D</sub> = 10A	-	25	32	0	
Drain-Source on-Resistance	,•	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 5A	-	31.5	40	mΩ	
Forward Transconductance <sup>4</sup>		<b>g</b> fs	V <sub>DS</sub> = 5V, I <sub>D</sub> = 10A	-	15.5	-	S	
Dynamic Characteristic	<b>s</b> <sup>5</sup>							
Input Capacitance		Ciss		-	1355	-		
Output Capacitance		Coss	$V_{DS} = 30V$ , $V_{GS} = 0V$ , $f = 1MHz$	-	60	-	pF	
Reverse Transfer Capacitance		Crss	-	-	49	-		
Gate Resistance		R <sub>G</sub>	f=1MHz	-	1.2	-	Ω	
Switching Characteristi	CS <sup>5</sup>			•		•		
Total Gate Charge		Qg		-	22	-	nC	
Gate-Source Charge		Q <sub>gs</sub>	$V_{GS} = 10V, V_{DD} = 30V,$ $I_{D} = 10A$	-	4.2	-		
Gate-Drain Charge		$\mathbf{Q}_{gd}$		-	6.9	-		
Turn-on Delay Time		t <sub>d(on)</sub>		-	6.4	-		
Rise Time		tr	$V_{GS} = 10V, V_{DD} = 30V,$	-	15.3	-		
Turn-off Delay Time		t <sub>d(off)</sub>	$R_G = 3\Omega$ , $I_D = 10A$	-	25	-	ns	
Fall Time		t <sub>f</sub>	1	-	7.6	-		
Body Diode Reverse Recovery Time		trr		-	26	-	ns	
Body Diode Reverse Recovery Charge		Qrr	- I <sub>F</sub> =10A, dI <sub>F</sub> /dt=100A/μs	-	45	-	nC	
Drain-Source Body Dio	de Character	istics	•				ı	
Diode Forward Voltage <sup>4</sup>		V <sub>SD</sub>	I <sub>S</sub> = 10A, V <sub>GS</sub> = 0V	-	-	1.2	V	
Continuous Source Current	T <sub>C</sub> =25℃	Is	-	-	_	20	Α	

#### Notes:

- 1. Repetitive rating, pulse width limited by junction temperature  $T_{J(MAX)}$ =150°C
- 2. The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}$ =25V,  $V_{\text{GS}}$ =10V, L=0.4mH,  $I_{\text{AS}}$ =14A
- 3. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
- 4. The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%.
- 5. This value is guaranteed by design hence it is not included in the production test.



# **Typical Characteristics**

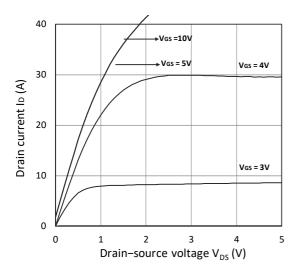


Figure 1. Output Characteristics

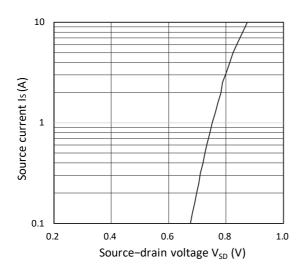


Figure 3. Forward Characteristics of Reverse

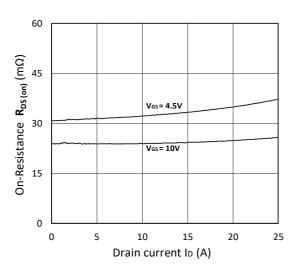


Figure 5.  $R_{DS(ON)}$  vs.  $I_D$ 

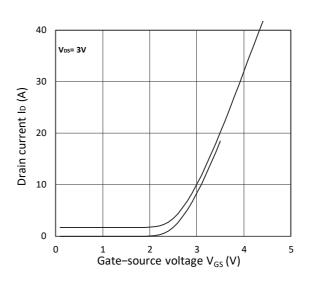


Figure 2. Transfer Characteristics

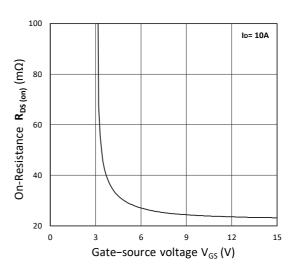


Figure 4.  $R_{DS(ON)}$  vs.  $V_{GS}$ 

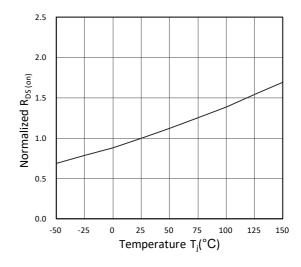


Figure 6. Normalized  $R_{DS(on)}$  vs. Temperature

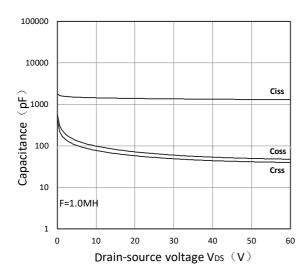


Figure 7. Capacitance Characteristics

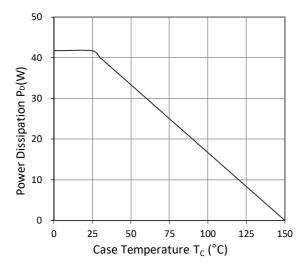


Figure 9. Power Dissipation

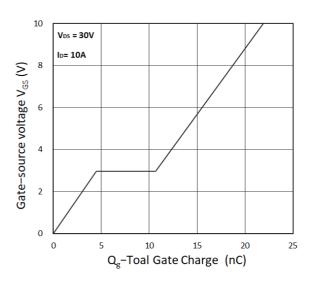


Figure 8. Gate Charge Characteristics

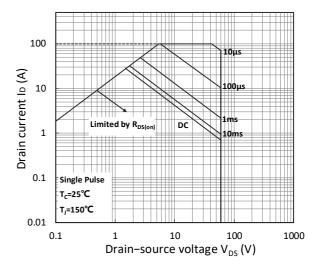


Figure 10. Safe Operating Area

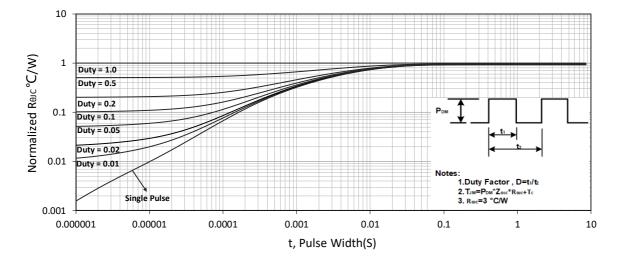
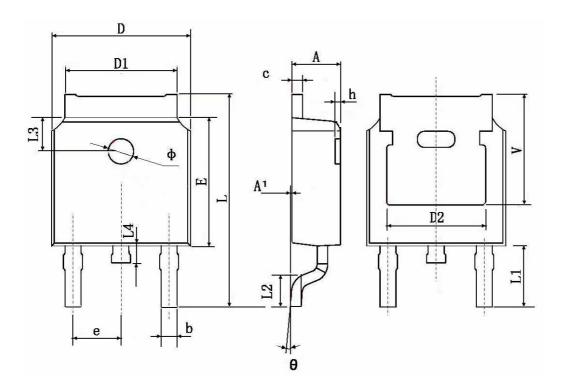


Figure 11. Normalized Maximum Transient Thermal Impedance



# **TO-252-2L Package Information**



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
Е	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP.		0.211 TYP.		



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